

TAS5707EVM (TAS5709EVM) User's Guide

This manual describes the operation of the TAS5707EVM (TAS5709EVM) to evaluate the performance of the TAS5707, TAS5707A, TAS5709, or TAS5709A integrated digital audio power amplifier. The TAS5707/09 is identical in function to the TAS5707A/09A, differing only in their I2C addresses. Some EVMs have the A versions of the device installed, TI recommends ensuring which one is being used by looking at the printed symbol on the device. The main contents of this document are:

- Details on how to properly connect a TAS5707/09 Evaluation Module (EVM) and the details of the EVM
- Details on how to set the I2C address of the TAS5707/07A and TAS5709/09A
- Details on how to install and use the GUI to program the TAS5707/09
- Details on how to use the audio processing features like EQ and DRC
- Quick-Start Guide for the common modes in which TAS5707EVM (TAS5709EVM) can be used

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 Microsoft, Windows are registered trademarks of Microsoft Corporation.
 I²C is a trademark of Philips Corporation.

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1 Overview

The TAS5707/09 evaluation module demonstrates the TAS5707/09 device from Texas Instruments. TAS5707 EVM is named "TAS5707EVM" and TAS5709 EVM is named as "TAS5709EVM". They both are same EVM except for the audio amplifier. The TAS5707 combines a high-performance PWM processor with a class-D audio power amplifier. This EVM can be configured with two bridge-tied loads (BTL) (2.0). For detailed information about the TAS5707/09 device, review the device data sheet ([SLOS550](#)). The Pulse Width Modulator (PWM) is based on TI's Equibit™ technology. TAS5709 has additional audio processing features like 3D, Bass Boost and 2-band DRC.

The EVM software with its graphic user interface (GUI) facilitates evaluation by providing access to the TAS5707/09 registers through a USB port. See the [Using the EVM Software](#) section for further details.

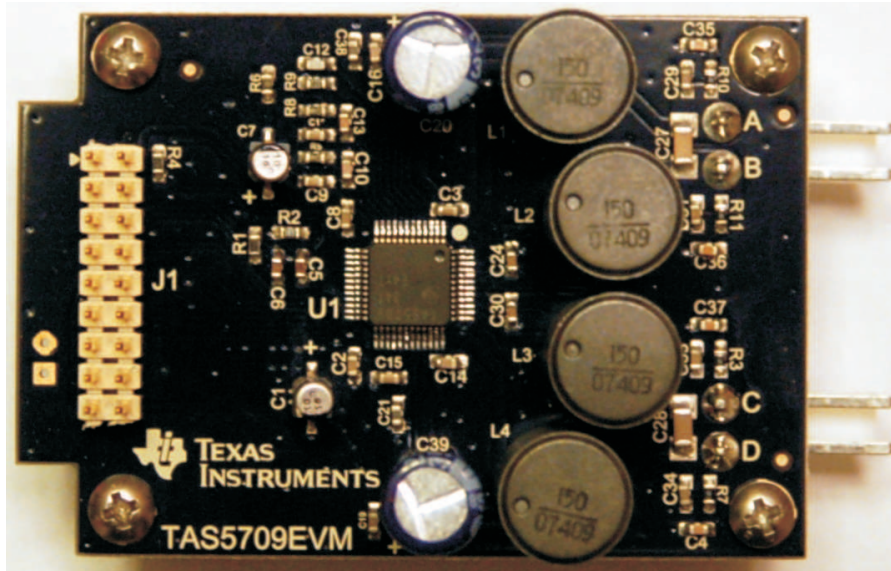
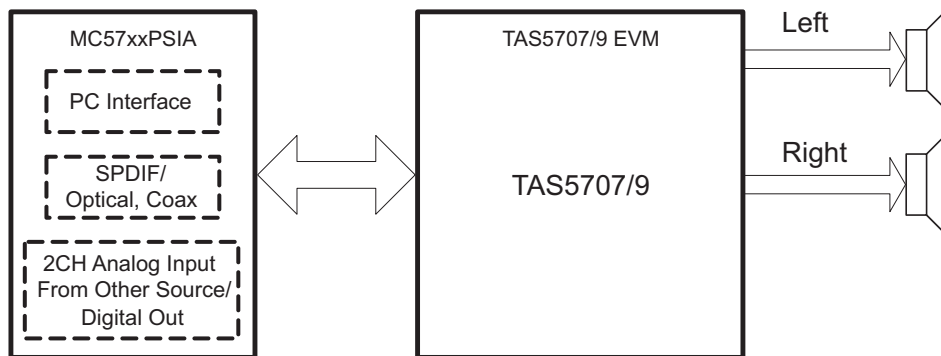


Figure 1. TAS5709EVM Printed-Circuit Board

The EVM together with other TI components on this board, is a complete 2.1-channel digital audio amplifier system. The MC57XXPSIA Controller board includes a USB interface, a digital input (SPDIF), analog inputs via the ADC, power inputs, and other features like a mute function and power down.



B0340-01

Figure 2. Complete System and EVM Signal Path Overview

1.1 TAS5707EVM (TAS5709EVM) and MC57xxPSIA Features

- Channel evaluation module design
- Self-contained protection systems and control pins
- USB interface
- Standard I²S data input using optical or coaxial inputs
- Analog input through analog-to-digital converter
- Subwoofer connection—the PWM terminal provides the PWM signal and power to an external subwoofer board
- Double-sided, plated-through PCB, 1-oz copper, 2 mm
- Access to control signal gain and data format through EVM-software GUI

2 Installation

This section describes the EVM and software installation.

2.1 EVM Installation

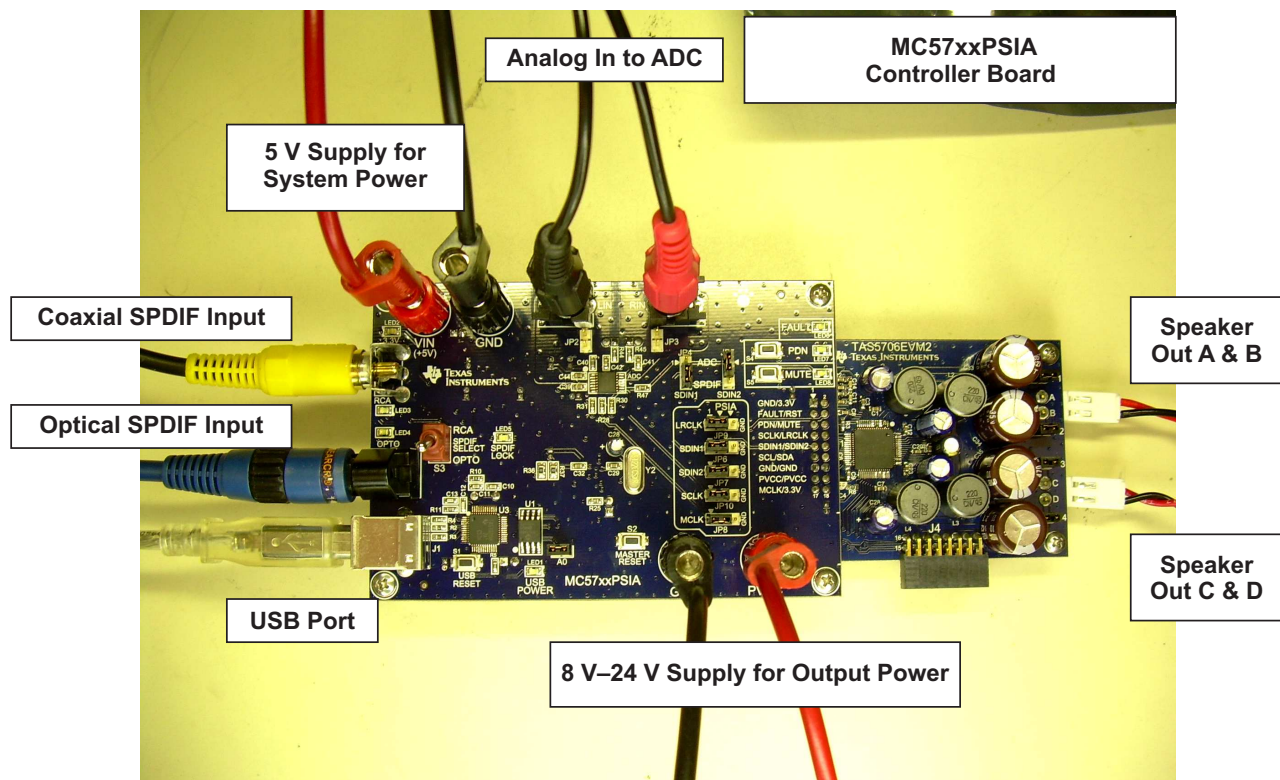


Figure 3. General Connection Picture

The following are the basic tools for the initial EVM power up.

- 5-V, 1-A power supply (VIN)
- 8–24-V, 4-A power supply (PVDD)
- Banana-style test leads for power supplies and speakers
- Optical or coaxial cable for SPDIF interface based on signal source
- USB cable
- EVM software
- Two 8-Ω speakers or loads

The following sections describe the TAS5707/09EVM board in regards to power supply (PSU) and system interfaces.

2.1.1 Connecting the TAS5707/09EVM to MC57xxPSIA

On the right side of the MC57xxPSIA is a terminal block and another on the left of the TAS5707/09EVM (labeled J1). Carefully place the MC57xxPSIA block above the TAS5707/09EVM block and gently push down.

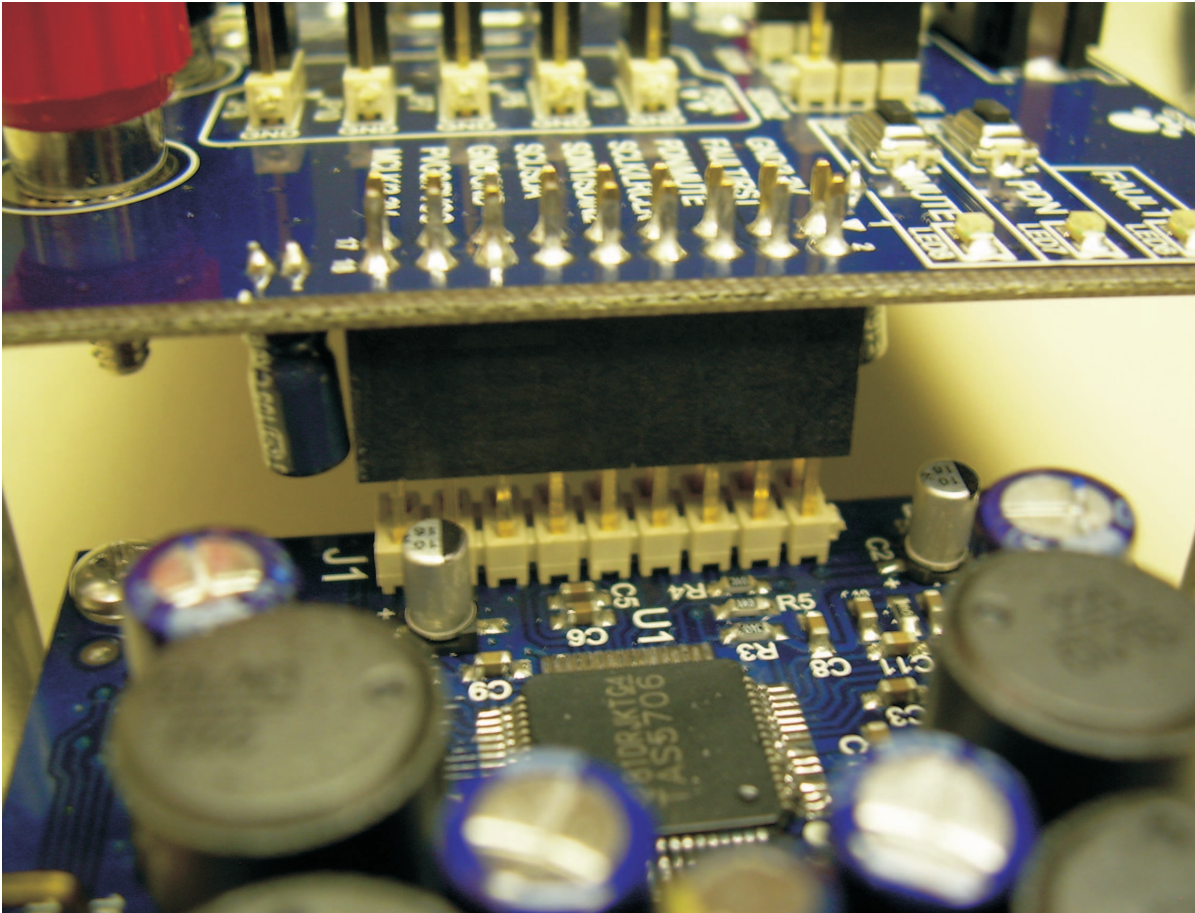


Figure 4. Connecting TAS5707/09EVM to MC57xxPSIA

2.1.2 PSU Interface

The TAS5707/09EVM is powered by two power supplies connected to the MC57xx controller board: a 5-V power supply (VIN), and a 8-V to 24-V (PVDD) power supply. The 3.3-V level is generated on the board by a voltage regulator from the 5-V supply.

NOTE: The power-supply cable length must be minimized. Increasing the length of the PSU cable increases the distortion of the amplifier at high output levels and low frequencies

The maximum output-stage supply voltage depends on the speaker load resistance. Check the recommended maximum supply voltage in the TAS5707/09 data sheet.

Table 1. Recommended Power Supplies

Description	Voltage Limitations (8-Ω Load)	Current Recommendations
System power supply	5 V	1 A
Output power stage supply	8–24 V	4 A ⁽¹⁾

⁽¹⁾ The rated current corresponds to two channels, full scale.

2.1.3 Loudspeaker Connectors

CAUTION

All speaker outputs are biased at $V_{CC}/2$ and must not be connected to ground (e.g., through an oscilloscope ground).

Loudspeaker connections vary by device setup. When connecting a speaker in BTL mode, connect the speaker's two terminals (A and B or C and D) across two outputs on the TAS5707/09EVM.

Speakers or loads can be connected to the outputs A-D with clip leads, or cables can be made with female connectors (JST VHR-2N) that can mate to male connectors on the EVM board.

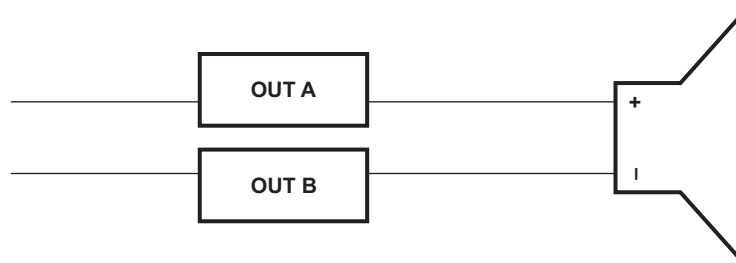


Figure 5. BTL Connection

2.1.4 USB Interface

The TAS5707/09 registers are accessed through I²C™ bus lines SDA and SCL. The USB circuit and USB connector on the MC57xxPSIA board facilitates the connection between a host computer and the device. The EVM USB circuit is powered by the 5-V USB line of the host PC and is independent of the power supplies available on the board. The USB device that is used is a TAS1020B from Texas Instruments.

2.1.5 Digital Audio Interface SPDIF

The Digital Audio Interface SPDIF (RCA/OPTO) accepts digital audio data using the I²S protocol. See the TAS5707/09 data sheet for more information.

The RCA connector and the OPTO connector are the two SPDIF interfaces on the MC57xxPSIA board. The switch S3 toggles between the OPTO and RCA connector to accommodate the signal source. When the RCA cable or optical cable is connected and the signal source is powered up, verify that the SPDIF lock indicator (blue LED5) illuminates, confirming that a viable signal is available to the device. Install a jumper on JP4 across the middle pin and the pin marked SPDIF to connect the digital source to SDIN1. Install a jumper on JP5 to connect the digital source to SDIN2.

For detailed information on how the data and clocks are provided to the TAS5707/09, see the schematic appearing at the end of this document and the DIR9001 device data sheet ([SLES198](#)).

2.1.6 ADC Interface

In the absence of a digital signal source, the PCM1808 ADC can be used to convert an analog audio signal to a digital signal to the TAS5707/09. The DIR9001 still provides clock signals to the ADC in this process. A 12-MHz crystal is installed on the MC57xxPSIA board. The ADC is an additional feature of this board to provide flexibility in sourcing an audio signal to the TAS5707/09. Review the PCM1808 data sheet ([SLES177](#)) for a detailed description of the ADC on this EVM. Install the jumper on JP4 across the middle pin and the pin marked ADC to select ADC as the source for SDIN1.

2.1.7 Board Power-Up General Guidelines

Connect the MC-57xx and the TAS5707/09EVM boards by locating pin 1 on each board, indicated by a small white triangle. The MC-57xx plugs down onto the TAS5707/09EVM board (i.e., the TAS5707/09EVM board fits underneath the MC57xxPSIA board). Pin 1 on each board must be connected to each other.

Install the EVM software on the PC before powering up the board. After connecting the loudspeakers or other loads, power supplies, and the data line, power up the 5-V power supply first; then power up the PVDD power supply. It is recommended initially to set the PVDD level to 10 V, then ramp it up to 20 V to verify cable connections.

2.2 Software Installation

Download the TAS570x GDE from the TI Web site. The TI Web site always has the latest release and any updates to versions of the GUI.

Execute the GUI install program, Setup.exe. Once the program is installed, the program group and shortcut icon is created in Start → Program → Texas Instruments Inc → TAS570X GDE. THE GUI come ups as shown in [Figure 6](#).

Select the appropriate tab, in this case, select TAS5705 tab. It has two subwindows. One shows the Process Flow window. From the Process Flow window, each of the signal processing function tools can be selected by clicking on it. The Biquad GUI and the DRC GUI can be opened by using the right button of the mouse. This window also shows Input select, Mode select, Channel, and Master Volume. All functions are shown in the order that they are in the device.

The other subwindow, Properties window, has the properties where a user can update by selecting from the available options. The properties available depends on the device selected. From the main window, the user must set three properties before connecting to the EVM.

Select the device Enable/Disable auto bank switch function, and set the sample rate. The TAS570x automatically detects sample rates. This setting is simply to synchronize the GUI and the device.

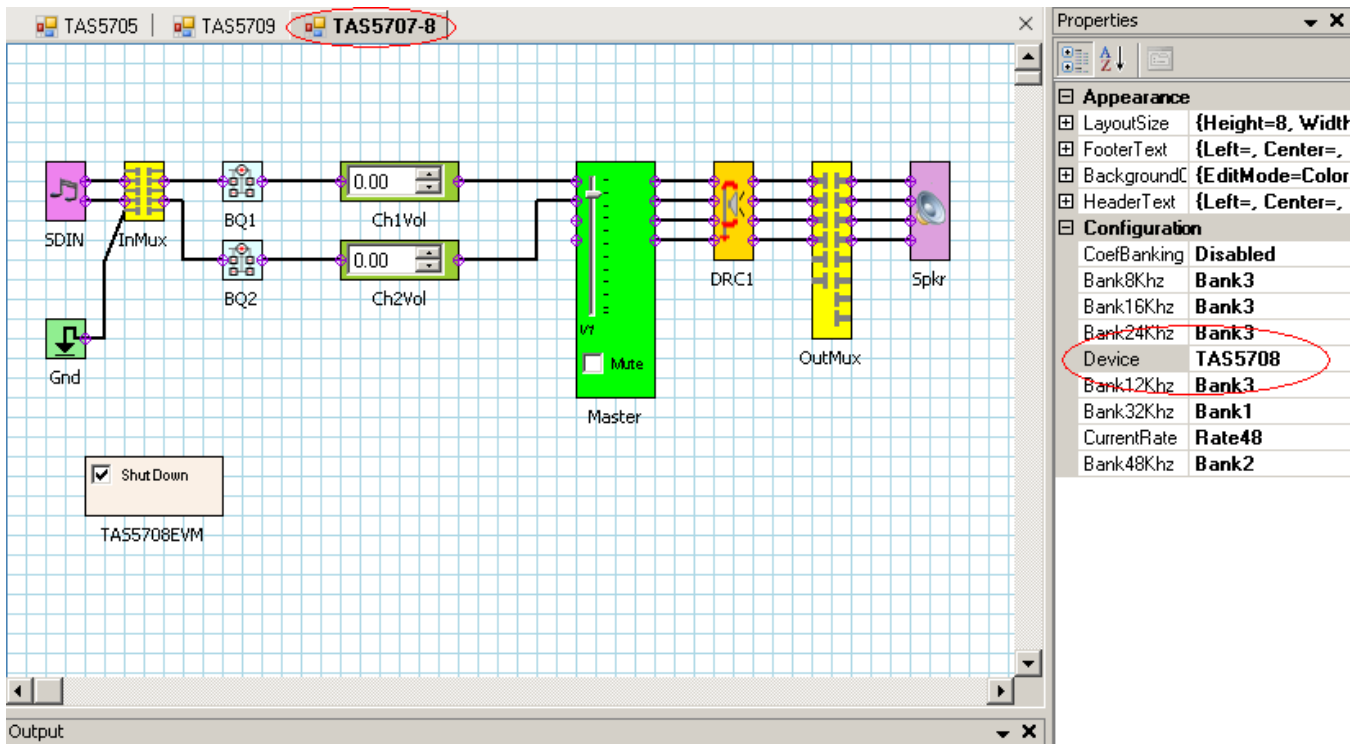


Figure 6. Process Flow for TAS5707 UG

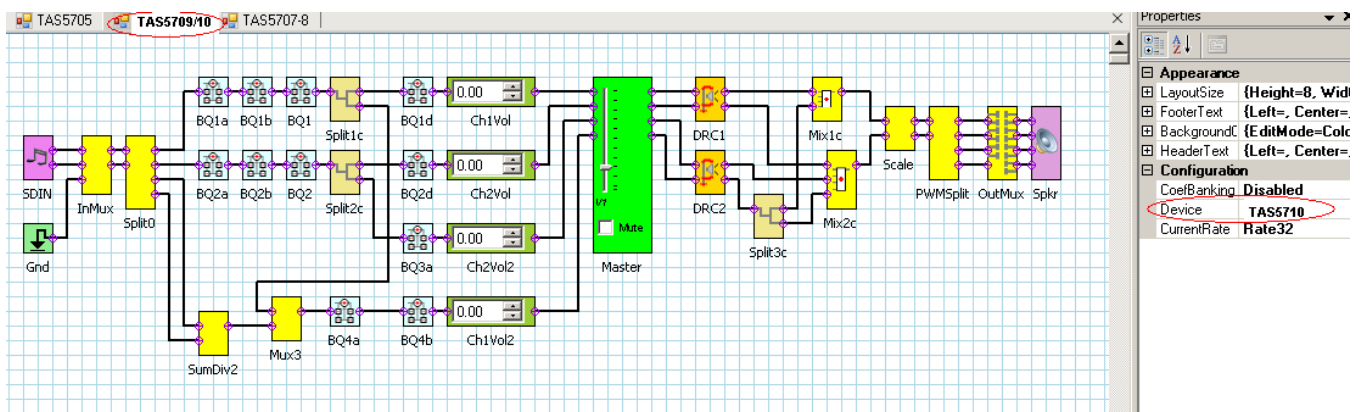


Figure 7. Process Flow for TAS5709 UG

2.3 I²C Address Setup

The TAS5707A/09A is identical in function to the TAS5707/09, but has a unique I²C device address. The address of the TAS5707/09 is 0x36. The address of the TAS5707A/09A is 0x3A. To configure the correct I²C address for these devices, the PPS12C environment variable must be created or modified.

1. Press *Start*, then right click on *My Computer* and select *Properties*, as shown in [Figure 8](#).

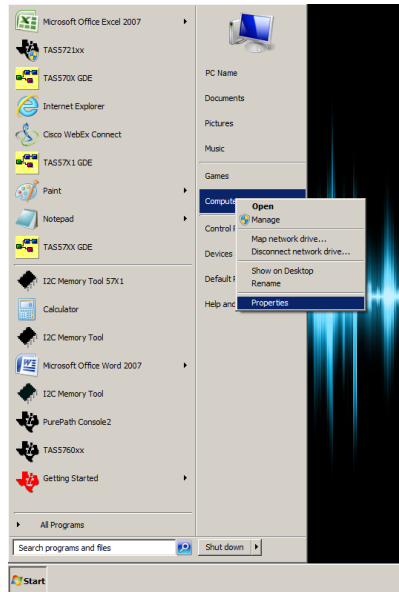


Figure 8. Selecting My Computer Properties from Microsoft® Windows® Start Menu

2. At the *System* window, click on *Advanced system settings*, then click on the *Environment Variables* button, as shown in [Figure 9](#).

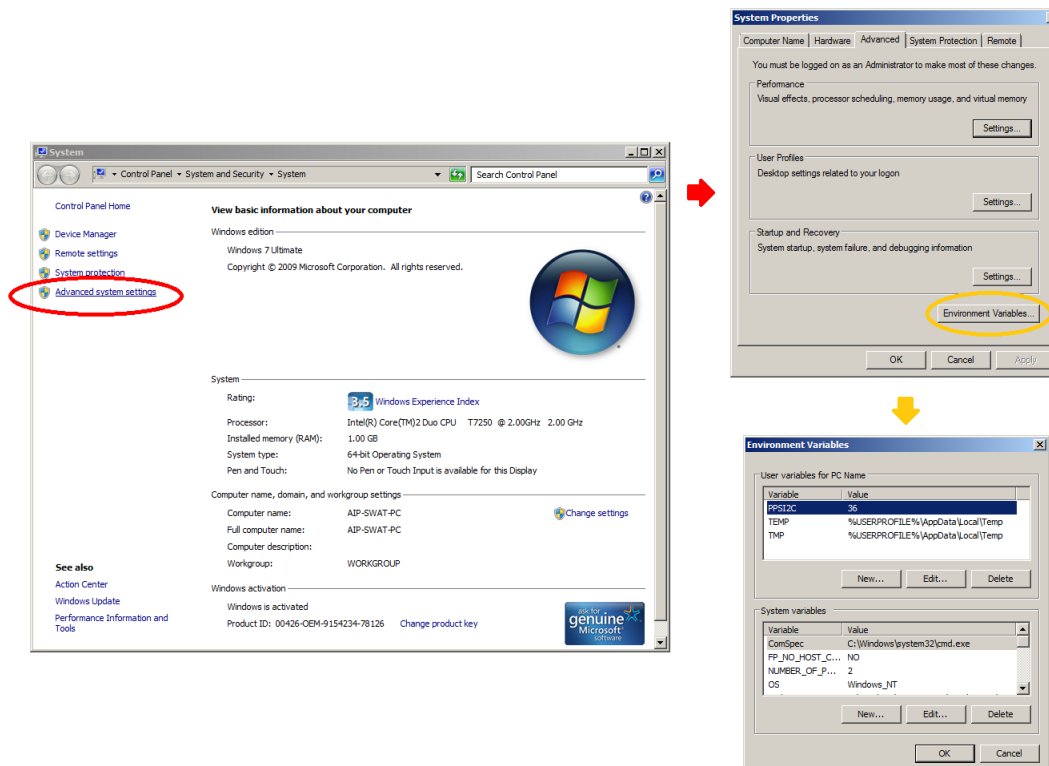


Figure 9. System Properties, Advanced Tab, and Environment Variables Windows

- In the *User Variables* section of the dialog, scroll through the list to see whether the variable PPSI2C shows. If the variable is not already listed, click the *New* button. If the variable name PPSI2C already exists in the list, click on PPSI2C to select it, and then click the *Edit* button. The *Edit User Variable* window appears, as shown in [Figure 10](#).

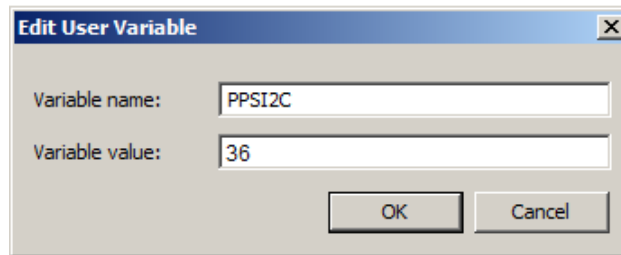


Figure 10. Edit User Variables Dialog

- In the window shown in [Figure 10](#), type "PPSI2C" as the *Variable name* (for new variables). The *Variable value* should be "36" for TAS5707/09 and "3A" for TAS5707A/09A. Click *OK* and close the dialog boxes.
Verify if the correct I²C address is used by looking at the symbolization name printed on the device installed in the EVM being used, as shown in [Figure 11](#).

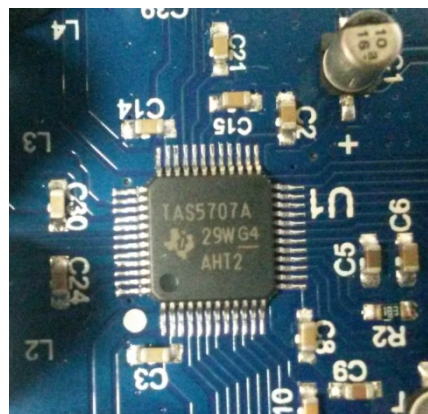


Figure 11. TAS5707A Installed on TAS5707EVM

3 Using the EVM Software

3.1 Connect the GUI to the EVM

Once the properties window selections have been made, go to the menu Target → Connect.

This sends the initialization commands to the device. Master volume is in mute. Select the master volume function. Type the required volume in the properties window. For TAS5707/09, type 0 dB. The difference is due the power stage gain in both devices. At this time, audio, if connected properly, plays through the device. Check All channel shutdown button. It must be un-checked. When the Connect command is issued, if an error appears indicating a USB problem, check the connections, and press the USB RESET button on the controller board. Then disconnect and re-connect from the Target menu.

3.2 I2C Memory Tool

This tool can be opened from GDE (Tools → I2C Memory Tool) or independent of GDE from Start → Program → Texas Instruments Inc → Memory Tool.

Select I2C as show in [Figure 12](#).

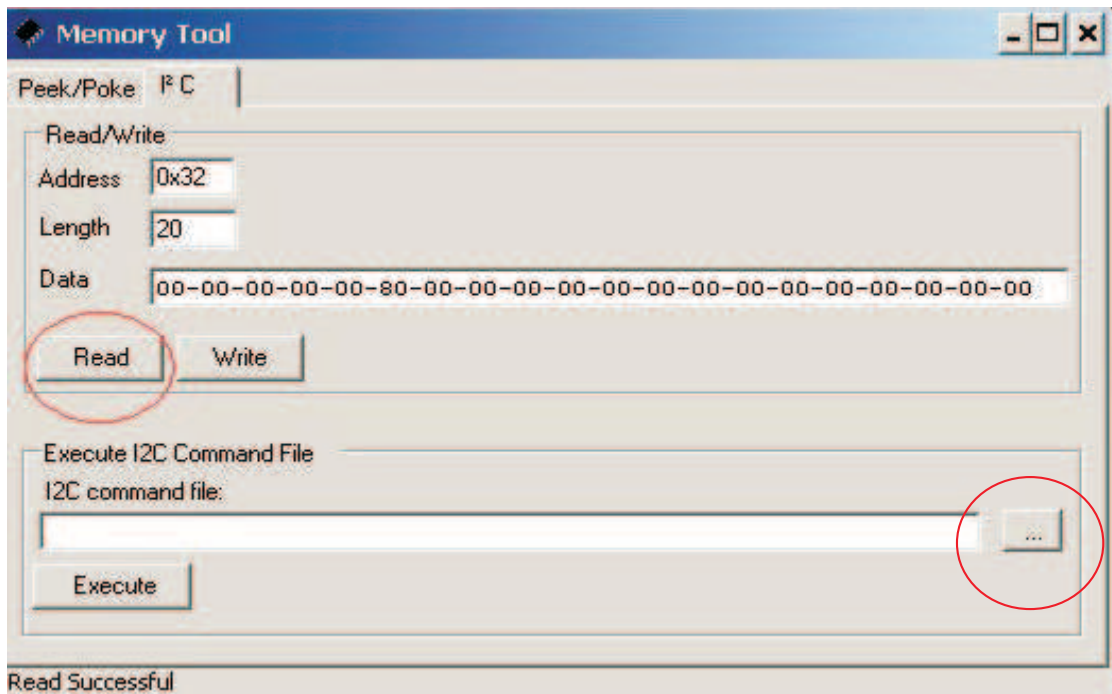


Figure 12. Memory Tool Window

I2C registers can be written or read using this tool. The I2C command file can be sent by selecting the command file and *Execute* command.

3.3 Volume Function

The Individual and Master volume can be selected, and the required volume value can be entered by typing on the property Window after selecting the function with the mouse (see [Figure 13](#)).

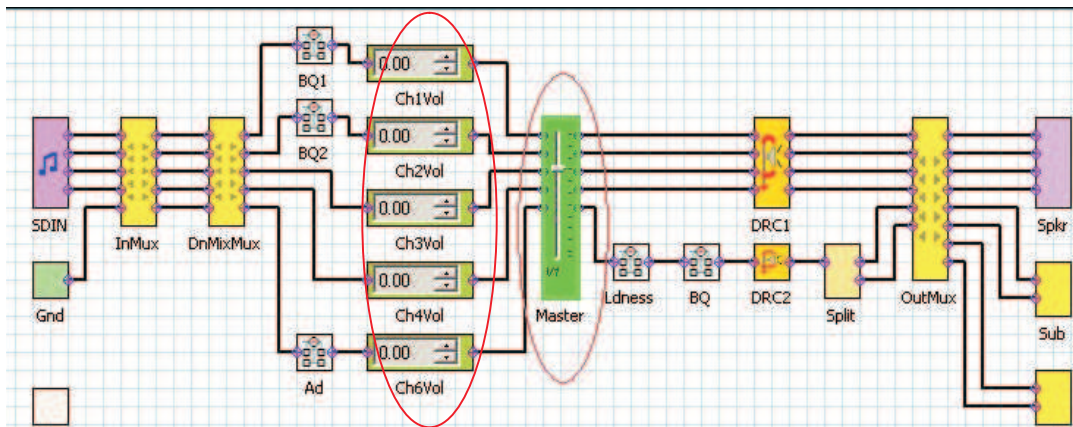


Figure 13. Volume Control

3.4 Biquad GUI

Using the right button of mouse, select Biquad GUI (Figure 14).

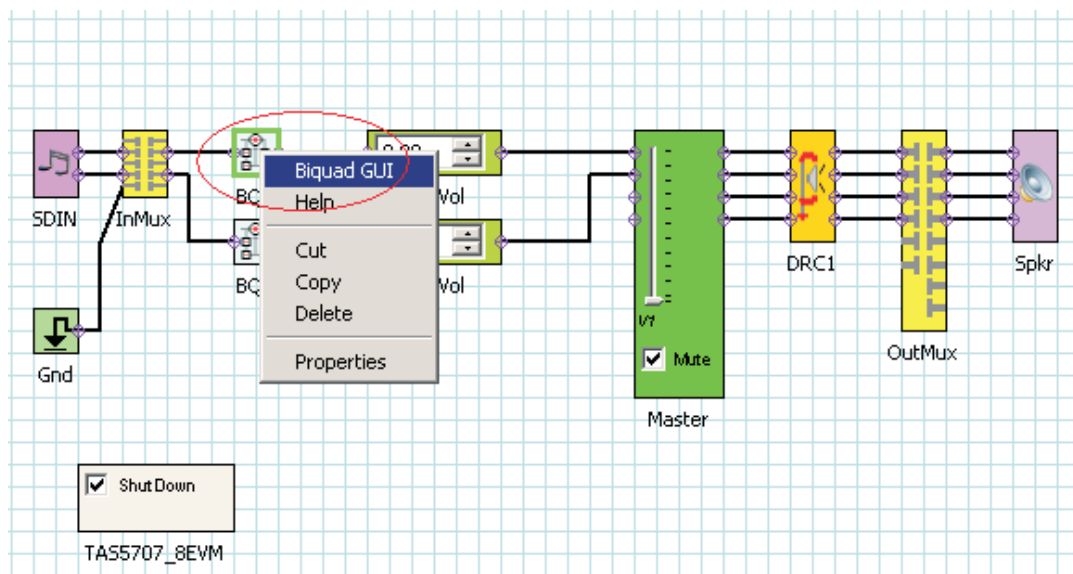


Figure 14. Selecting Biquad GUI

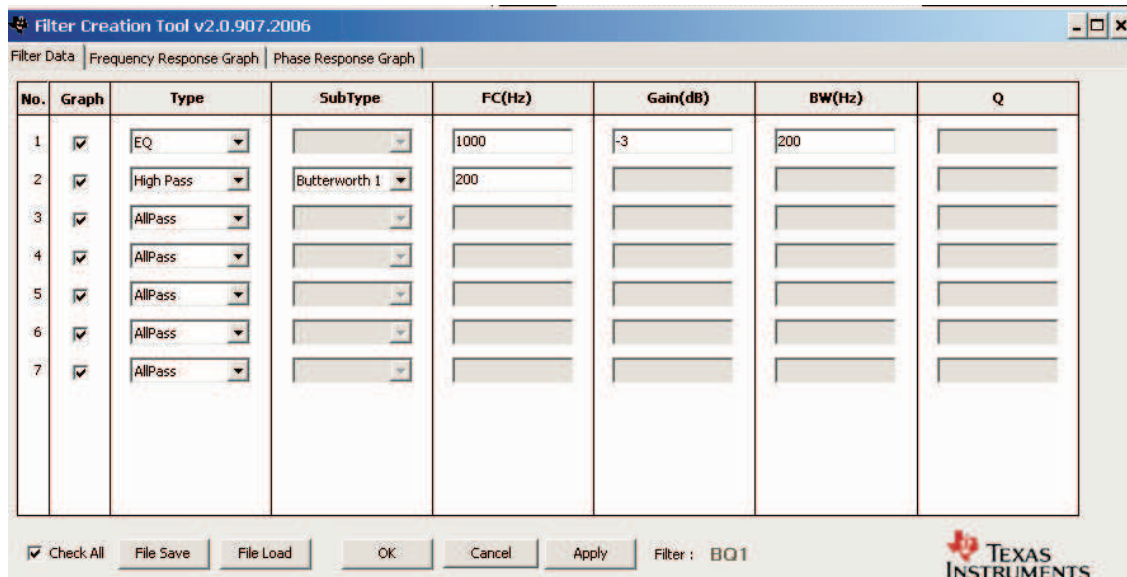


Figure 15. Filter Creation Tool Window

A check mark selects the Biquad. If not selected, the Biquad is in ALL PASS Mode.

The frequency response for the current settings can be viewed and adjusted in **Frequency Response Window** Tab (Figure 15). The Individual Biquad Gains must be within ± 12 db.

Apply from the filter data window sends all the three banks of coefficients (providing auto bank is enabled).

3.5 DRC GUI

Clicking on the function selects DRC GUI (Figure 16). Click on the DRC function, and check to see if DRC is enabled in the property window.

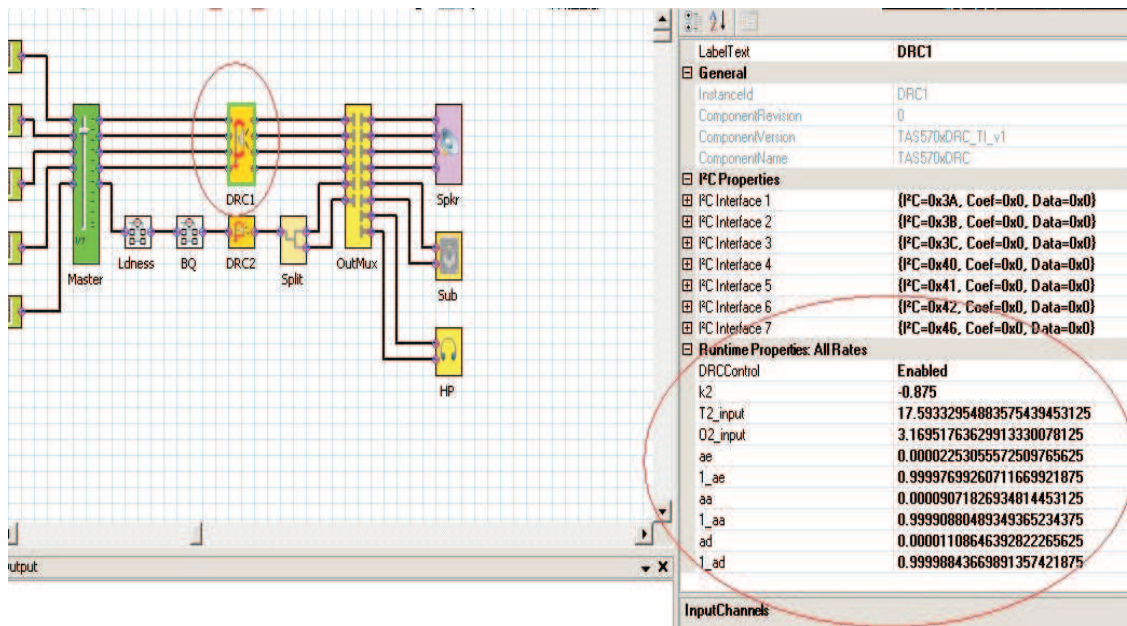


Figure 16. DRC Parameters

Next, using the right button of the mouse, select **Activate DRC GUI** (Figure 17).

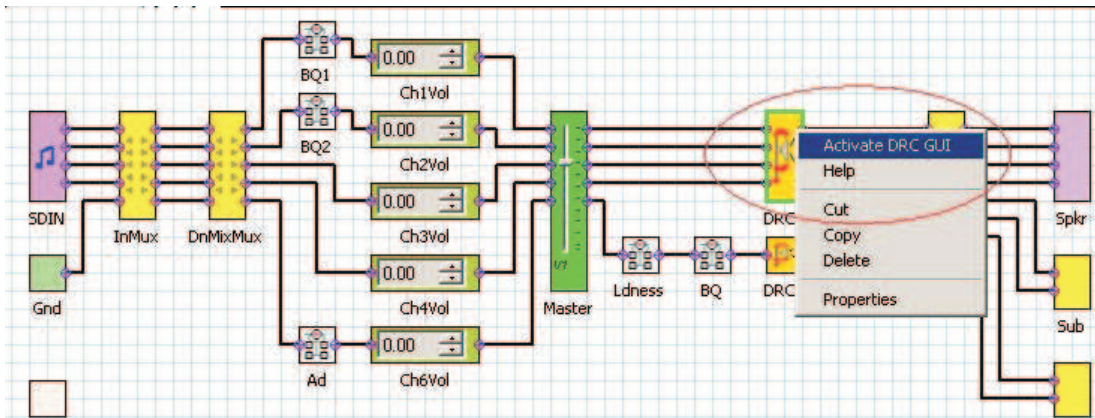


Figure 17. Activating the DRC GUI

Set the **compression ratio** to a value between 1 and 50.

The **offset** has a range at ± 6 dB. A value of 0 is illegal. If no offset is required, set the offset to 0. Offset is generally not required in a DRC application because it just provides a gain.

Threshold is selected with a value of 0 to -72 dB.

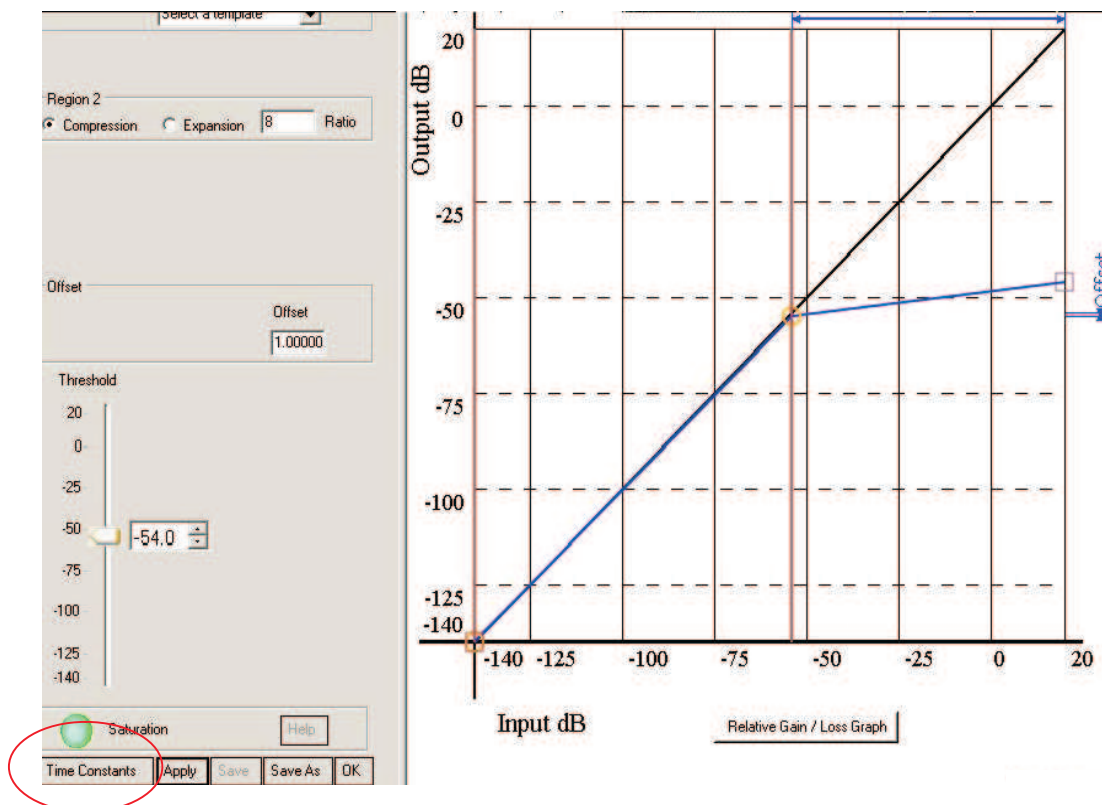


Figure 18. Time Constants Button

Time constants: Select the time constants to adjust the energy, attack, and decay filters (Figure 18).

3.5.1 MODULATION SCHEMES

Common Configurations:

1. 2 × BTL BD
2. 2 × BTL AD Mode

Note:

- AD : AD Modulation-Outputs are 180° out of phase
- BD : BD Modulation
- BTL : Bridge-Tied Load

3.5.1.1 2 X BTL BD (BD mode)

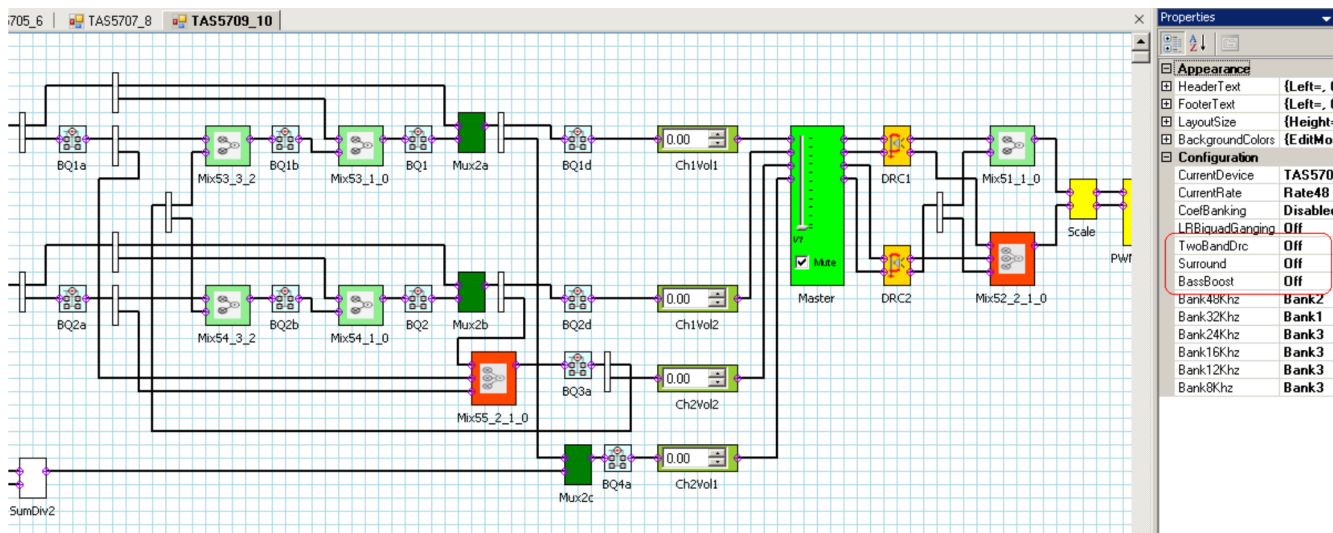
1. Set up the hardware.
2. Select the Input MUX from GDE. In the properties window, select BD Mode.
3. GDE: **Target > Connect.**
4. Finally uncheck the **shutdown** box to bring the device out of Shutdown mode, and adjust the **Master Volume** as desired.

3.5.1.2 2 X BTL AD(Default: AD mode)

1. Set up the hardware .
2. Select the Input MUX from GDE. In the properties window, select AD Mode
3. GDE: **Target > Connect.**
4. Finally uncheck the **shutdown** box to bring the device out of Shutdown mode, and adjust the **Master Volume** as desired.

4 Advanced Audio Processing Features in TAS5709

TAS5709 Process Structure as shown in GDE:



C001

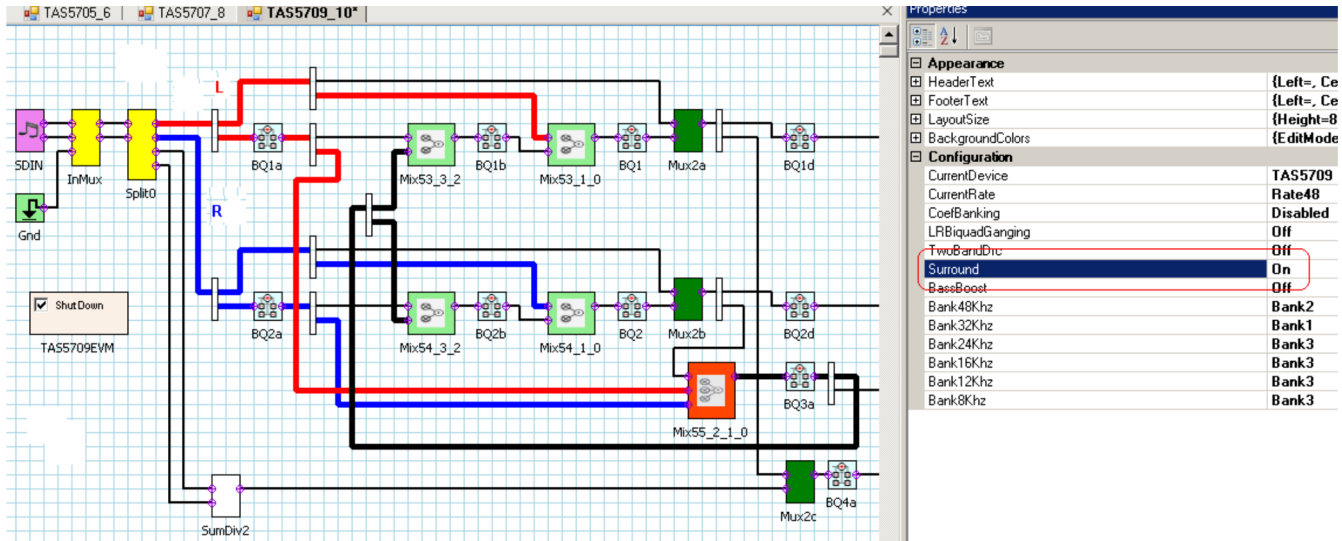
TAS5709 process diagram has three audio processing functions in the main properties window:

1. **Surround (3D): ON/OFF**
2. **Bass Boost (Pseudo Bass): ON/OFF**
3. **Two-Band DRC (2-band DRC): ON/OFF**

Each of these features are explained as follows:

1. **Surround (3D): ON/OFF**

Turn it ON. Then L-R terms gets mixed with raw L and R after band-pass filtering. L-signal is RED, R-signal is BLUE and L-R-signal is BLACK.

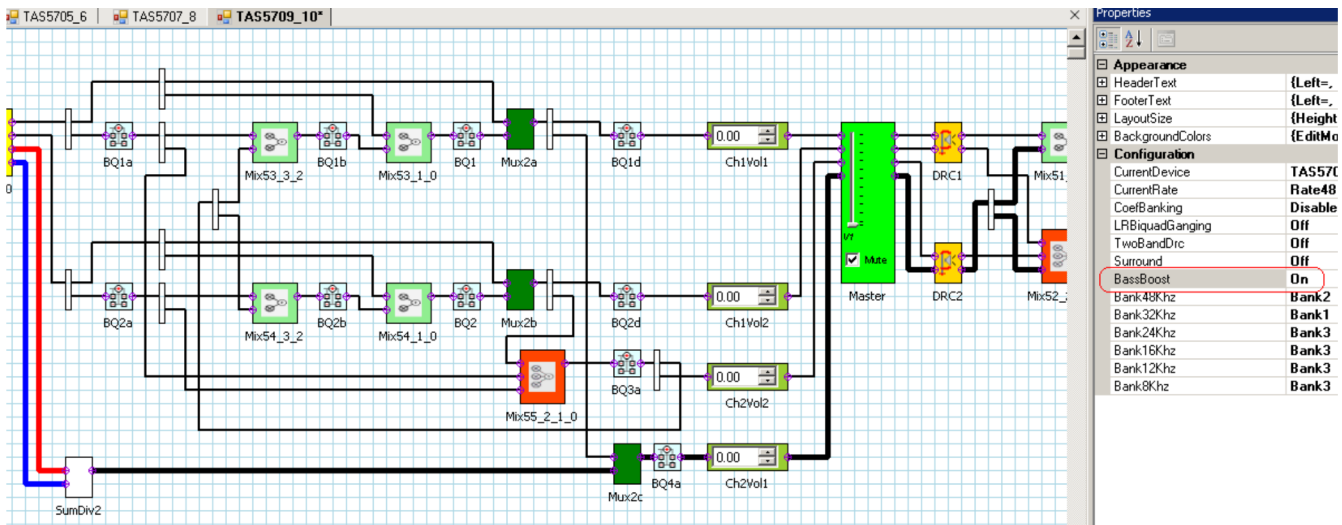


C002

Biquads and mixers can be adjusted to fine-tune 3D.

2. Bass Boost (Pseudo Bass): ON/OFF

(L+R)/2 signal is low-pass filtered to get the Bass signal and then applied a boost before mixing with L and R channels.

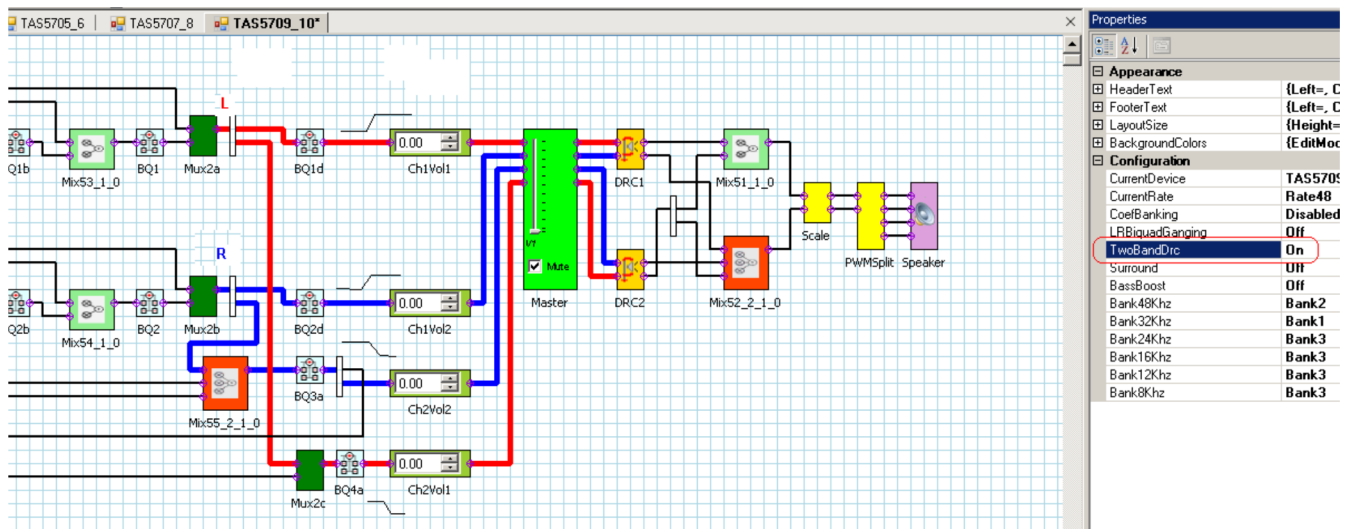


C003

3. Two-Band DRC (2-band DRC): ON/OFF

L and R signals are split into two paths: one path with high-frequency components (high pass) and the other with low-frequency components (low pass).

High frequency of both L and R has one DRC-ganged and low-frequency paths have another DRC-ganged. This allows both high- and low-frequency components to have different thresholds.



C004

Both DRCs can be programmed separately.

5 Jumpers and Control Utilities on MC57xxPSIA board

5.1 RCA/OPTICAL Jumpers

Select the jumper to reflect the source whether it is RCA or OPTICAL.

5.2 Switches

Reset is an active-low function. Pressing the master reset switch (S2) resets the TAS5707/09 device; USB RESET (S1) resets the USB bus. Pressing PDNZ (S4) powers down the TAS5707/09, and pressing MUTE (S5) mutes (volume mute) the TAS5707/09.

5.3 LED Indicators

LED1 : USB Power connector installed at J1.

LED2 : 3.3V Power is valid.

LED3: RCA connection made

LED4: Optical connection made

LED5: SPDIF signal locked

LED6: FAULT (Not used with TAS5707/09EVM)

LED7: PDN switch (S4) is depressed.

LED8: MUTE switch (S5) is depressed.

6 Board Layouts, Bill of Materials, and Schematic

6.1 TAS5709EVM (TAS5707EVM) and MC57xxPSIA Board Layouts

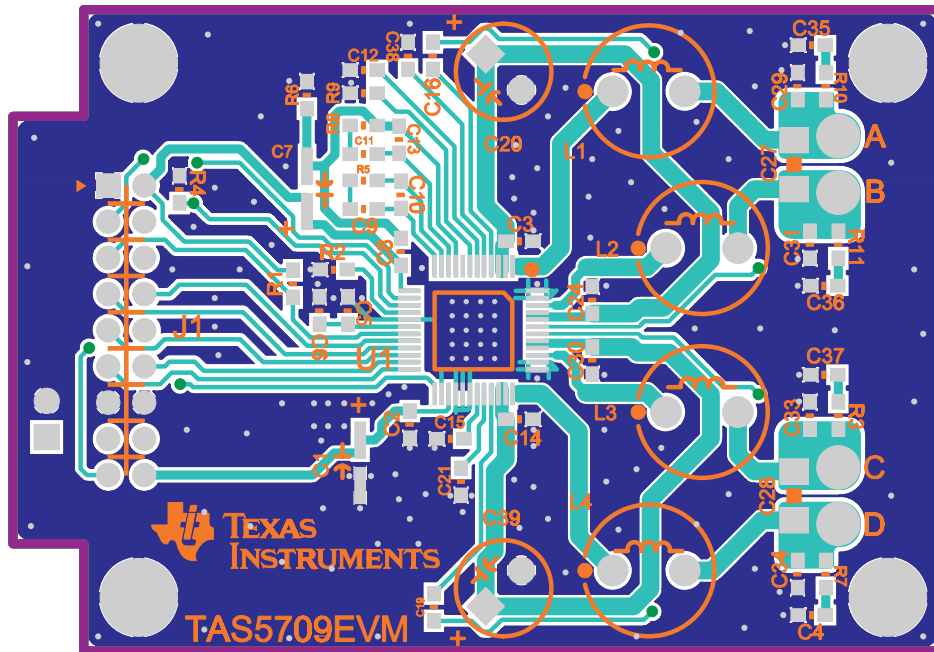


Figure 19. TAS5709EVM(TAS5707EVM) Top Composite Assembly

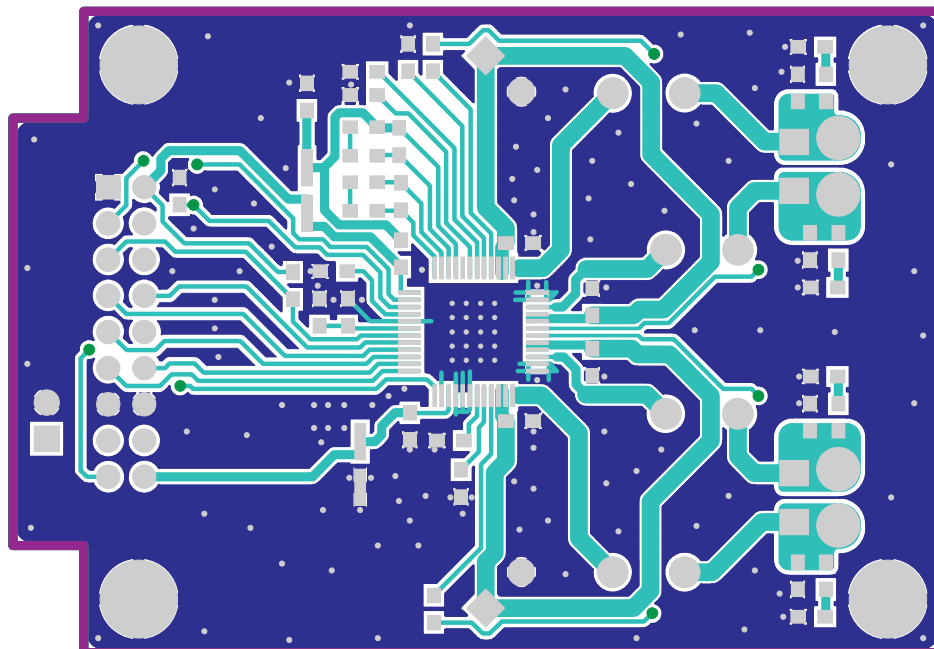


Figure 20. TAS5709EVM (TAS5707EVM) Top Copper Assembly

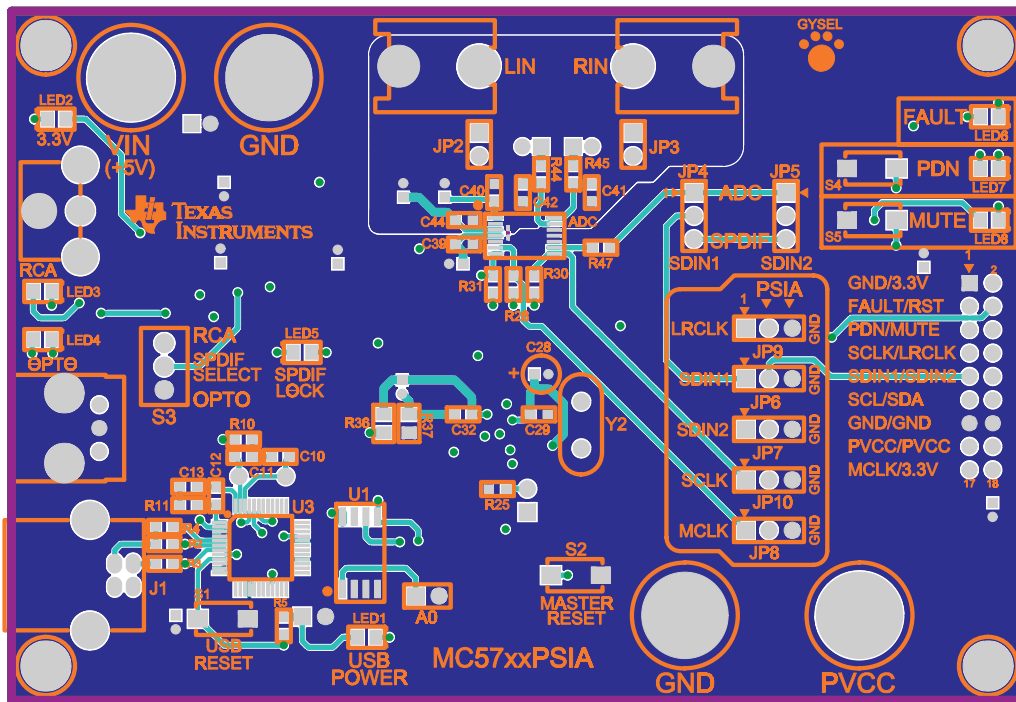


Figure 21. MC57xxPSIA Top Assembly

6.2 Bill of Materials

Table 2. Bill of Materials for TAS5709EVM

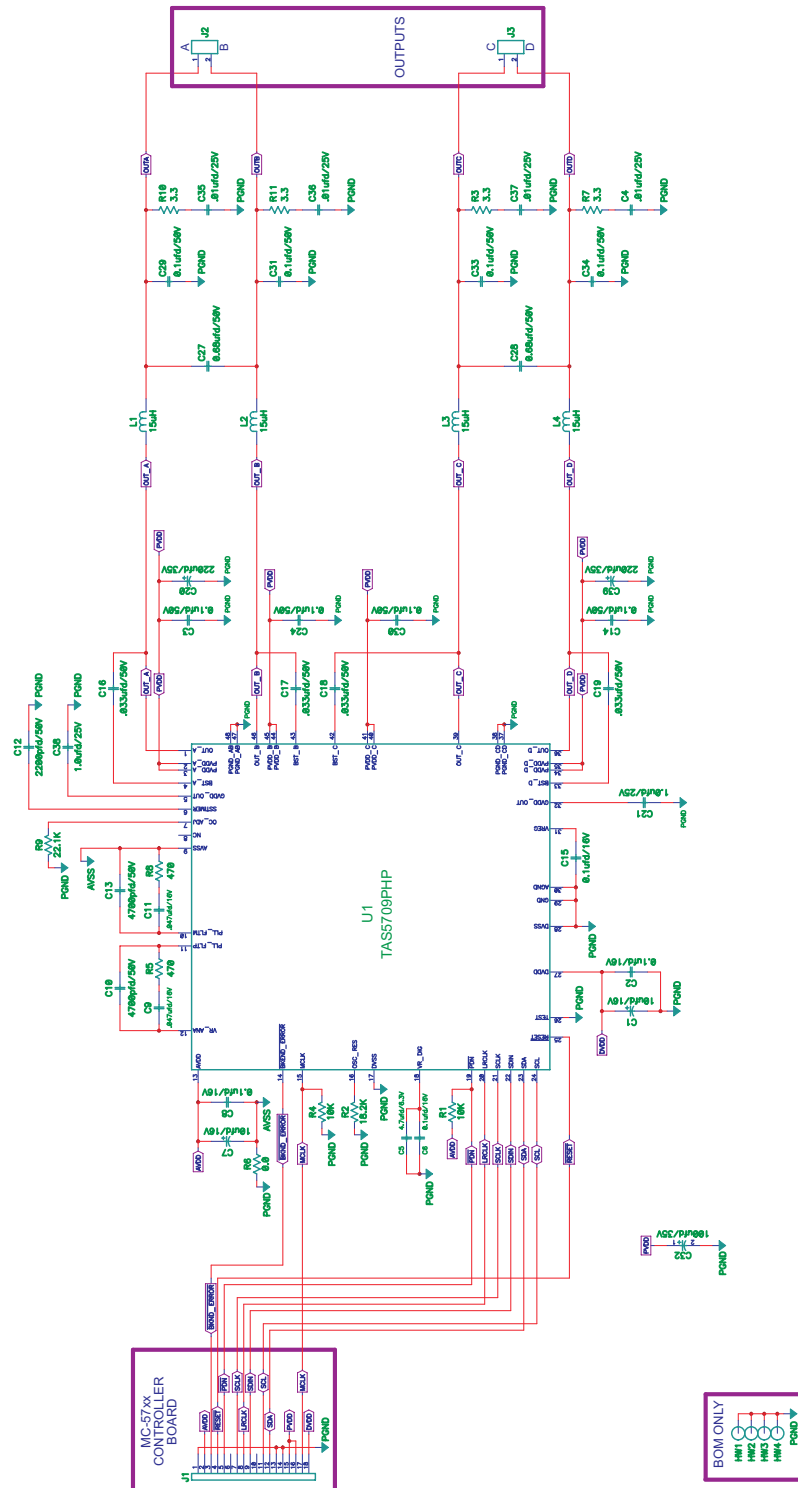
MANU Part No.	QTY	REF DES	Vendor Part No.	Description	Vendor	MANU
TI-SEMICONDUCTORS						
TAS5709PHP	1	U1	TAS5709PHP	15W DIGAMP PLUS EQ-DRC HTQFP48-PHP	Texas Instruments	Texas Instruments
CAPACITORS						
ECJ-1VB1H222K	1	C12	PCC1776CT	CAP 2200PFD 50V CERM 0603 X7R	Digi-Key	Panasonic
ECJ-1VB1H472K	2	C10, C13	PCC1780CT	CAP 4700PFD 50V CERM 0603 X7R	Digi-Key	Panasonic
ECJ-1VB1E103K	4	C4, C35–C37	PCC1763CT	CAP 0.01UFD 25V CERM 0603 X7R	Digi-Key	Panasonic
ECJ-1VB1H333K	4	C16–C19	PCC2284CT	CAP 0.033UFD 50V CERM 0603 X7R	Digi-Key	Panasonic
ECJ-1VB1C473K	2	C9, C11	PCC1758CT	CAP 0.047UFD 16V CERM 0603 X7R	Digi-Key	Panasonic
ECJ-1VB1C104K	4	C2, C6, C8, C15	PCC1762CT	CAP 0.1UFD 16V CERM 0603 X7R	Digi-Key	Panasonic
GRM188R71H104KA93D	8	C3, C14, C24, C29–C31, C33, C34	490-1519-1	CAP 0.1UFD 50V CERM 0603 X7R	Digi-Key	Murata
C1206C684K5RACTU	2	C27, C28	399-3500-1	CAP 0.68UFD 50V CERM 1206 X7R ROHS	Digi-Key	Kemet
TMK107BJ105KA-T	2	C21, C38	587-1248-1	CAP 1.0UFD 25V CERM 0603 X5R ROHS	Digi-Key	Taiyo Yuden
C1608X5R0J475M	1	C5	445-1417-1	CAP 4.7UFD 6.3V CERM 0603 X5R	Digi-Key	TDK Corp.
ECE-V1CS100SR	2	C1, C7	PCE3061CT	CAP 10UFD 16V ALUM ELEC SMD VSA	Digi-Key	Panasonic
ECA-1VM101	1	C32	P10418TB	CAP 100UFD 35V RAD ALUM ELEC M	Digi-Key	Panasonic
ECA-1VM221BJ	2	C20, C39	P10419TB	CAP 220UFD 35V ALUM ELEC M-SERIES ROHS	Digi-Key	Panasonic
RESISTORS						
ERJ-3GEY0R00V	1	R6	P0.0GCT	RES 0.0 OHM 1/16W 5% SMD 0603	Digi-Key	Panasonic
9C06031A3R30JLHFT	4	R3, R7, R10, R11	311-3.3GCT	RES 3.3 OHM 1/16W 5% SMD 0603	Digi-Key	Yageo
ERJ-3GEYJ471V	2	R5, R8	P470GCT	RES 470 OHM 1/10W 5% SMD 0603	Digi-Key	Panasonic
9C06031A1002JLHFT	2	R1, R4	311-10KGCT	RES 10K OHM 1/16W 5% SMD 0603	Digi-Key	Panasonic
9C06031A1822FKHFT	1	R2	311-18.2KHCT	RES 18.2K OHM 1/10W 1% SMD 0603	Digi-Key	Yageo
ERJ-3EKF2212V	1	R9	P22.1KHCT	RES 22.1K OHM 1/16W 1% SMD 0603	Digi-Key	Panasonic
INDUCTORS						
A7503AY-150M	4	L1–L4	A7503AY-150M	INDUCTOR, SERIES 11RHBP, 15UH	Toko America	Toko America
HEADERS						
B2PS-VH	2	J2, J3	455-1255	Header, 2 Pin Male, PCB-RA, TIN, W/Lock	Digi-Key	JST
PBC09DAAN	1	J1	S2011E-09	HEADER, 2X9 PIN MALE, PCB STRAIGHT GOLD ROHS	Digi-Key	Sullins
STANDOFFS AND HARDWARE						
PMS 440 0025 PH	4	HW1-HW4	H342	4-40 Screw, Steel 0.250 IN	Digi-Key	Building Fasteners
2027	4	HW1-HW4	2027K	Standoff, 4-40, 0.5INx3/16IN, ALUM RND F-F	Digi-Key	Keystone Electronics
Component Count:	62					
COMPONENTS NOT ASSEMBLED						
C32						
COMPONENTS MISSING FROM SEQUENCE						
C22, C23, C25, C26						

Table 3. Bill of Materials for TAS5707EVM

MANU Part No.	QTY	REF DES	Vendor Part No.	Description	Vendor	MANU
TI-SEMICONDUCTORS						
TAS5707PHP	1	U1	TAS5707PHP	15W DIGAMP PLUS EQ-DRC HTQFP48-PHP	Texas Instruments	Texas Instruments
CAPACITORS						
ECJ-1VB1H222K	1	C12	PCC1776CT	CAP 2200PFD 50V CERM 0603 X7R	Digi-Key	Panasonic
ECJ-1VB1H472K	2	C10, C13	PCC1780CT	CAP 4700PFD 50V CERM 0603 X7R	Digi-Key	Panasonic
ECJ-1VB1E103K	4	C4, C35–C37	PCC1763CT	CAP 0.01UFD 25V CERM 0603 X7R	Digi-Key	Panasonic
ECJ-1VB1H333K	4	C16–C19	PCC2284CT	CAP 0.033UFD 50V CERM 0603 X7R	Digi-Key	Panasonic
ECJ-1VB1C473K	2	C9, C11	PCC1758CT	CAP 0.047UFD 16V CERM 0603 X7R	Digi-Key	Panasonic
ECJ-1VB1C104K	4	C2, C6, C8, C15	PCC1762CT	CAP 0.1UFD 16V CERM 0603 X7R	Digi-Key	Panasonic
GRM188R71H104KA93D	8	C3, C14, C24, C29– C31, C33, C34	490-1519-1	CAP 0.1UFD 50V CERM 0603 X7R	Digi-Key	Murata
C1206C684K5RACTU	2	C27, C28	399-3500-1	CAP 0.68UFD 50V CERM 1206 X7R ROHS	Digi-Key	Kemet
TMK107BJ105KA-T	2	C21, C38	587-1248-1	CAP 1.0UFD 25V CERM 0603 X5R ROHS	Digi-Key	Taiyo Yuden
C1608X5R0J475M	1	C5	445-1417-1	CAP 4.7UFD 6.3V CERM 0603 X5R	Digi-Key	TDK Corp.
ECE-V1CS100SR	2	C1, C7	PCE3061CT	CAP 10UFD 16V ALUM ELEC SMD VSA	Digi-Key	Panasonic
ECA-1VM101	1	C32	P10418TB	CAP 100UFD 35V RAD ALUM ELEC M	Digi-Key	Panasonic
ECA-1VM221BJ	2	C20, C39	P10419TB	CAP 220UFD 35V ALUM ELEC M-SERIES ROHS	Digi-Key	Panasonic
RESISTORS						
ERJ-3GEY0R00V	1	R6	P0.0GCT	RES 0.0 OHM 1/16W 5% SMD 0603	Digi-Key	Panasonic
9C06031A3R30JLHFT	4	R3, R7, R10, R11	311-3.3GCT	RES 3.3 OHM 1/16W 5% SMD 0603	Digi-Key	Yageo
ERJ-3GEYJ471V	2	R5, R8	P470GCT	RES 470 OHM 1/10W 5% SMD 0603	Digi-Key	Panasonic
9C06031A1002JLHFT	2	R1, R4	311-10KGCT	RES 10K OHM 1/16W 5% SMD 0603	Digi-Key	Panasonic
9C06031A1822FKHFT	1	R2	311-18.2KHCT	RES 18.2K OHM 1/10W 1% SMD 0603	Digi-Key	Yageo
ERJ-3KEF2212V	1	R9	P22.1KHCT	RES 22.1K OHM 1/16W 1% SMD 0603	Digi-Key	Panasonic
INDUCTORS						
A7503AY-150M	4	L1–L4	A7503AY-150M	INDUCTOR, SERIES 11RHBP, 15UH	Toko America	Toko America
HEADERS						
B2PS-VH	2	J2, J3	455-1255	Header, 2 Pin Male, PCB-RA, TIN, W/Lock	Digi-Key	JST
PBC09DAAN	1	J1	S2011E-09	HEADER, 2X9 PIN MALE, PCB STRAIGHT GOLD ROHS	Digi-Key	Sullins
STANDOFFS AND HARDWARE						
PMS 440 0025 PH	4	HW1-HW4	H342	4-40 Screw, Steel 0.250 IN	Digi-Key	Building Fasteners
2027	4	HW1-HW4	2027K	Standoff, 4-40, 0.5INx3/16IN, ALUM RND F-F	Digi-Key	Keystone Electronics
Component Count:	62					
COMPONENTS NOT ASSEMBLED						
C32						
COMPONENTS MISSING FROM SEQUENCE						
C22, C23, C25, C26						

6.3 Schematics

The schematic for TAS5709EVM (TAS5707EVM) follows. The schematics for MC57xxPSIA appear on the following pages.



Revision History

Changes from B Revision (February 2009) to C Revision**Page**

-
- Added *fC Address Setup* section. 9
-

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

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 - 3.1.1 *Notice applicable to EVMs not FCC-Approved:*

This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.
 - 3.1.2 *For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:*

CAUTION

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210

Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

3.3 Japan

3.3.1 *Notice for EVMs delivered in Japan:* Please see http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。
http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page

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If User uses EVMs in Japan, User is required by Radio Law of Japan to follow the instructions below with respect to EVMs:

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

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4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.

4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.

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